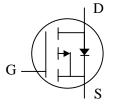


P-channel Enhancement-mode Power MOSFET

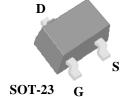
Simple Drive Requirement
Lower On-resistance
Surface Mount Device
RoHS-compliant, halogen-free



-20V
$97 \text{m}\Omega$
-3.3A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.



The AP2301AGN-HF-3 is in the popular SOT-23 small surface-mount package which is widely used in commercial and industrial applications where a small board footprint is required.

This device is well suited for use in medium current applications such as load switches and DC-DC converters.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	±8	V
I _D at T _A =25°C	Continuous Drain Current ³	-3.3	А
I _D at T _A = 70°C	Continuous Drain Current ³	-2.7	А
I _{DM}	Pulsed Drain Current ¹	-15	А
P _D at T _A =25°C	Total Power Dissipation	1.38	W
	Linear Derating Factor	0.01	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient	90	°C/W

Ordering Information

AP2301AGN-HF-3TR RoHS-compliant halogen-free SOT-23, shipped on tape and reel, 3000pcs/reel



Electrical Specifications at T_i=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V, I_D =-250uA	-20	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V_{GS} =-4.5V, I_{D} =-3A	-	-	97	mΩ
		V _{GS} =-2.5V, I _D =-2.6A	-	-	130	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=-250uA$	-0.3	-	-1	V
g _{fs}	Forward Transconductance	V_{DS} =-5V, I_{D} =-3A	-	14	-	S
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-20V, V_{GS} =0V	-	-	-1	uA
	Drain-Source Leakage Current (T _j =55°C)	V _{DS} =-16V, V _{GS} =0V	-	-	-1	uA
I _{GSS}	Gate-Source Leakage	$V_{GS}=\pm 8V, V_{DS}=0V$	-	-	±100	nA
Q_g	Total Gate Charge ²	I _D =-3A	-	12.5	21	nC
Q_{gs}	Gate-Source Charge	V _{DS} =-16V	-	1.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V _{GS} =-4.5V	-	3.5	-	nC
t _{d(on)}	Turn-on Delay Time ²	V _{DS} =-10V	-	8	-	ns
t _r	Rise Time	I _D =-1A	-	17	-	ns
t _{d(off)}	Turn-off Delay Time	$R_G=3.3\Omega$, $V_{GS}=-5V$	-	24	-	ns
t _f	Fall Time	$R_D=10\Omega$	-	33	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	920	-	pF
C _{oss}	Output Capacitance	V _{DS} =-20V	-	90	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	85	-	pF
R_g	Gate Resistance	f=1.0MHz	-	4.5	6.8	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V_{SD}	Forward On Voltage ²	I _S =-1.2A, V _{GS} =0V	1	ı	-1.2	V
trr	Reverse Recovery Time ²	I _S =-3.3A, V _{GS} =0V,	•	25	-	ns
Qrr	Reverse Recovery Charge	dl/dt=100A/µs	•	12	-	nC

Notes:

- 1. Pulse width limited by maximum junction temperature.
- 2. Pulse test pulse width \leq 300 μ s , duty cycle \leq 2%
- 3. Surface mounted on 1in² copper pad of FR4 board; 270°C/W when mounted on minimum copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

Typical Electrical Characteristics

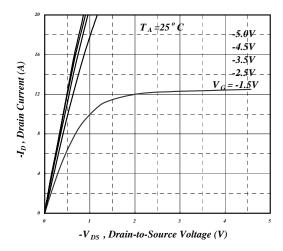


Fig 1. Typical Output Characteristics

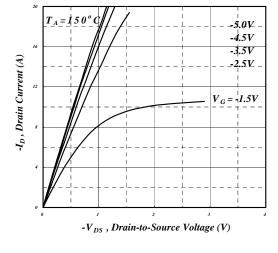


Fig 2. Typical Output Characteristics

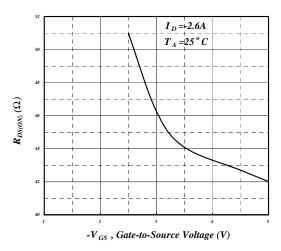


Fig 3. On-Resistance vs. Gate Voltage

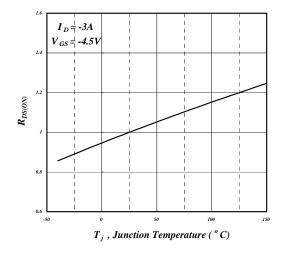


Fig 4. Normalized On-Resistance vs. Junction Temperature

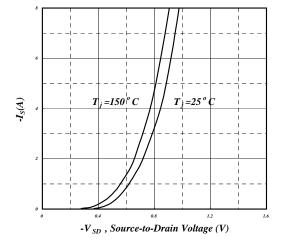


Fig 5. Forward Characteristic of Reverse Diode

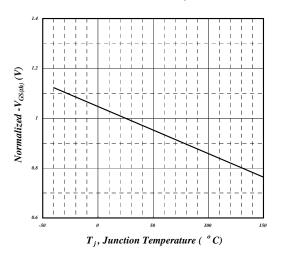


Fig 6. Gate Threshold Voltage vs.
Junction Temperature

Typical Electrical Characteristics (cont.)

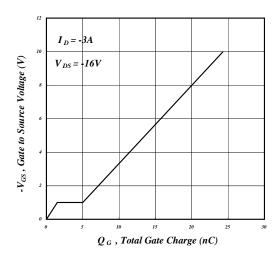
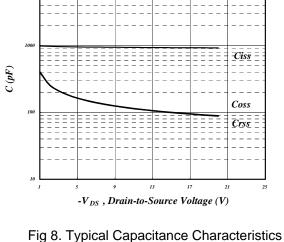


Fig 7. Gate Charge Characteristics



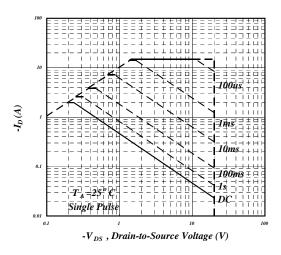


Fig 9. Maximum Safe Operating Area

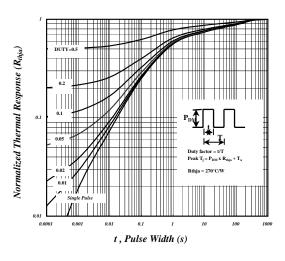


Fig 10. Effective Transient Thermal Impedance

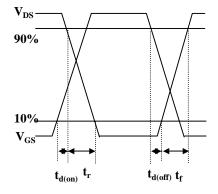


Fig 11. Switching Time Waveform

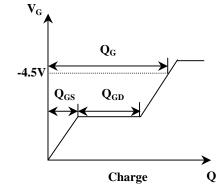
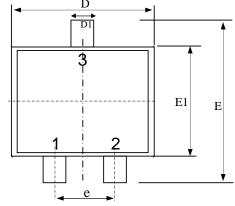
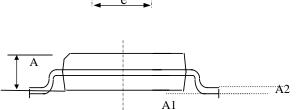


Fig 12. Gate Charge Waveform

Package Dimensions: SOT-23

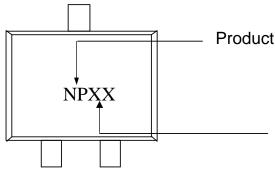




SYMBOLS	Millimeters			
	MIN	NOM	MAX	
A	1.00	1.15	1.30	
A1	0.00		0.10	
A2	0.10	0.15	0.25	
D1	0.30	0.40	0.50	
e	1.70	2.00	2.30	
D	2.70	2.90	3.10	
Е	2.40	2.65	3.00	
E1	1.40	1.50	1.60	

- 1. All dimensions are in millimeters.
- 2. Dimensions do not include mold protrusions.

Marking Information: SOT-23



Product: NP = AP2301AGN-HF-3

Date/lot code

For details of how to convert this to standard YYWW date code format, please contact us directly.